

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT

## CONVEYING PARTY DATA

Name	Execution Date
HUAN-CHU HUANG	05/13/2020
JUNYONG LIU	05/13/2020
HONG LIN	05/13/2020
HAO SUN	05/13/2020
ZHIXING QI	05/12/2020
MINHUI ZENG	05/14/2020
YANCHAO ZHOU	05/13/2020
JINGWEI LI	05/14/2020
TAO MA	05/14/2020

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## PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	16885717

## CORRESPONDENCE DATA

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PATENT

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**NAME OF SUBMITTER:** YUN H. CHOE

**SIGNATURE:** /Yun H. Choe/

**DATE SIGNED:** 05/28/2020

**Total Attachments: 3**

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<b>ASSIGNMENT OF RIGHTS, TITLE AND INTEREST IN INVENTION</b>
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*This is an assignment of the following rights, title and interest (check all that apply):*

- United States of America rights, title and interest in the invention*
- Foreign rights, title and interest in the invention*
- United States Patent Application Serial No.*  
*Date of Execution: \_\_\_\_\_ Date of Filing: \_\_\_\_\_*
- United States Provisional Patent Application Serial No.*
- United States Patent No(s). \_\_\_\_\_*
- International (PCT) Patent Application Serial No**
- Other (specify): \_\_\_\_\_*

*Title of the Invention:*

AN INTEGRATION MODULE OF MILLIMETER-WAVE AND NON-MILLIMETER-WAVE ANTENNAS
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*Inventors (assignors):*

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*Assignee:*

Name	Address
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<b>EAST CHINA RESEARCH INSTITUTE OF MICROELECTRONICE</b>	No. 19, Hehuan Road, High-Tech Development Zone, Hefei, Anhui Province, China

WHEREAS, we, the above-identified Inventors, have invented certain new and useful improvements in the Invention identified above and described in the above-identified patent application(s) and /or patent(s) (hereinafter referred to as "Invention");

And, whereas we desire to assign our above-identified rights, title and interest in the Invention to the above-identified Assignee;

NOW, this indenture witnesseth, that in consideration of the sum of ONE DOLLAR (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration;

We hereby assign, sell and transfer our above-identified rights, title and interest in said Invention, said application(s) as identified above, including any divisions, continuations, and continuations-in-part thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said Invention, and in and to any and all reissues and reexaminations thereof, which may be granted or have granted for said Invention, and in and to any and all priority rights, Convention rights, and other benefits accruing or to accrue to us with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, unto said Assignee;

And we hereby authorize and request the Commissioner of Patents and Trademarks to issue any United States Letters Patent which may issue for said Invention to said Assignee, as assignee of the whole right, title and interest thereto;

And we further agree to sign and execute all necessary and lawful future documents, including applications for foreign patents, for filing divisions, continuations and continuation-in-part of said application for patent and/or for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid Invention, as the Assignee or its Designee(s) may from time to time require and prepare at its own expense.

The undersigned hereby grant(s) the firm of LUCAS & MERCANTI, LLP, located at 30 Broad Street, New York, New York, 10004, the power to insert on this assignment any further identification which may be necessary or desirable in order to comply with the rules of the United States Patent Office for recordation of this document.

*Inventors' Signatures:*

Name	Signature	Date
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